

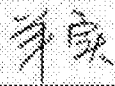
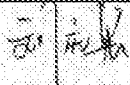
PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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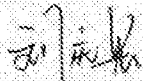
EPAS ID: PAT5562510

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHI YANG	05/07/2019
XU ZHOU	05/07/2019
RECEIVING PARTY DATA	
Name:	CHENGDU SILICON TECHNOLOGY CO., LTD.
Street Address:	FLOORS 1-3, BUILDING 5, NO. 200, TIANFU FIFTH STREET
Internal Address:	HIGH-TECH ZONE
City:	CHENGDU, SICHUAN
State/Country:	CHINA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16467108
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Address Line 2:	GENERAL POST OFFICE
Address Line 4:	HONG KONG, CHINA
ATTORNEY DOCKET NUMBER:	SSUIP-19003-USPT
NAME OF SUBMITTER:	CHARLES HO
SIGNATURE:	/Charles Ho/
DATE SIGNED:	06/10/2019
Total Attachments: 2	
source=Executed assignment#page1.tif	
source=Executed assignment#page2.tif	

ASSIGNMENT - Patent Application		Docket Number: SSUIP-19003-USPT
Whereas, the Assignor, comprising the following named inventors:		
ASSIGNOR(s)/ INVENTOR(s)	Shi Yang and Xu Zhou	
made an invention entitled: <u>SYSTEM AND METHOD FOR GRANULATING AND MOLDING SILICON LIQUID</u>		
for which an application for Letters Patent of the United States: (Select one of the following):		
☒ is executed concurrently herewith ☐ was filed in the U.S. Patent and Trademark Office on _____ as U.S. Patent Application Serial No. _____		
ASSIGNEE (Full Name, Address and Country)	ChengDu Silicon Technology Co., Ltd. Floors 1-3, Building 5, No. 200, Tianfu Fifth Street, High-tech Zone, Chengdu, Sichuan China	
is desirous of acquiring our entire right, title and interest in and to said invention and the Letters Patent to be obtained therefor, Now, therefore, in consideration of the payment by Assignee to Assignor of a sum corresponding to One Dollar (\$1.00), and for other good and valuable consideration, the receipt of which is hereby acknowledged, Assignor, intending to be legally bound, hereby sells, assigns and transfers to Assignee, its successors and assigns, the full and exclusive right, title and interest in and to said invention, all applications for Letters Patent for said invention, including all divisions, continuations, and continuations-in-part thereof, all rights to claim priority based thereon, and all Letters Patent, including reissues, to be obtained therefor, including any and all foreign patent rights in this invention corresponding thereto. Assignor hereby warrants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment. Assignor agrees it shall be legally bound, upon request of the Assignee or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the Assignor has knowledge or possession, relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the Assignee, and to execute all instruments proper to carry out the intent of this instrument. In witness whereof, this Assignment is executed on the day indicated below.		

	Typed or Printed Name	Signature	Date
SIGNATURE	Shi Yang		May 7, 2019
	Qinghong Liu		
	* Witness to Assignor	* Witness to Assignor	

ASSIGNMENT - Patent Application		Docket Number: SSUIP-19003-USPT
Whereas, the Assignor, comprising the following named inventors:		
ASSIGNOR(s)/ INVENTOR(s)	Shi Yang and Xu Zhou	
made an invention entitled: <u>SYSTEM AND METHOD FOR GRANULATING AND MOLDING SILICON LIQUID</u>		
for which an application for Letters Patent of the United States: (Select one of the following):		
☒ is executed concurrently herewith ☐ was filed in the U.S. Patent and Trademark Office on _____ as U.S. Patent Application Serial No. _____		
ASSIGNEE (Full Name, Address and Country)	ChengDu Silicon Technology Co., Ltd. Floors 1-3, Building 5, No. 200, Tianfu Fifth Street, High-tech Zone, Chengdu, Sichuan China	
is desirous of acquiring our entire right, title and interest in and to said invention and the Letters Patent to be obtained therefor, Now, therefore, in consideration of the payment by Assignee to Assignor of a sum corresponding to One Dollar (\$1.00), and for other good and valuable consideration, the receipt of which is hereby acknowledged, Assignor, intending to be legally bound, hereby sells, assigns and transfers to Assignee, its successors and assigns, the full and exclusive right, title and interest in and to said invention, all applications for Letters Patent for said invention, including all divisions, continuations, and continuations-in-part thereof, all rights to claim priority based thereon, and all Letters Patent, including reissues, to be obtained therefor, including any and all foreign patent rights in this invention corresponding thereto. Assignor hereby warrants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment. Assignor agrees it shall be legally bound, upon request of the Assignee or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the Assignor has knowledge or possession, relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the Assignee, and to execute all instruments proper to carry out the intent of this instrument. In witness whereof, this Assignment is executed on the day indicated below.		

	Typed or Printed Name	Signature	Date
SIGNATURE	Xu Zhou		May 7, 2019
	Qinghong Liu		
	* Witness to Assignor	* Witness to Assignor	